

EE143 Lab Week 3 Measurement Checklist:

1) Lithography

Time (sec)	
Softbake:	
Exposure:	
Developer:	
Hardbake:	

Linewidth (um)		
Nominal	Measured	% Overetch
2		
3		
4		
8		

Notes: 1 tick mark in the right eyepiece of microscope is 1um under 100X

2) Etch:

Oxide Etch Time:

3) Measurements after Process Completion:

Field Oxide Thickness (Nanospec):

ACTV Sheet Resistivity (Control Wafer):

Questions:

Calculate % overetch of the linewidth patterns

What was a visual method for determining completion of etching?